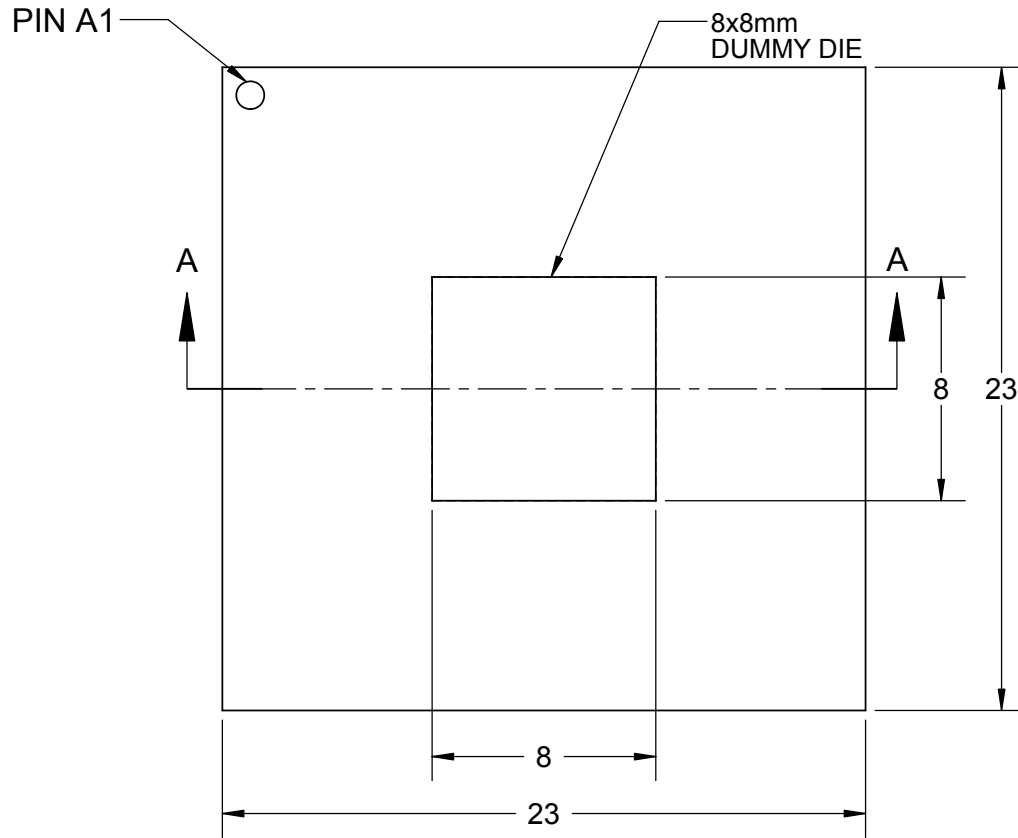
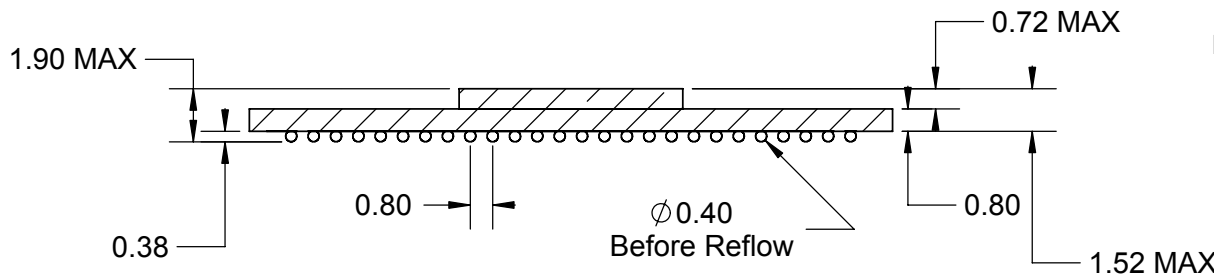
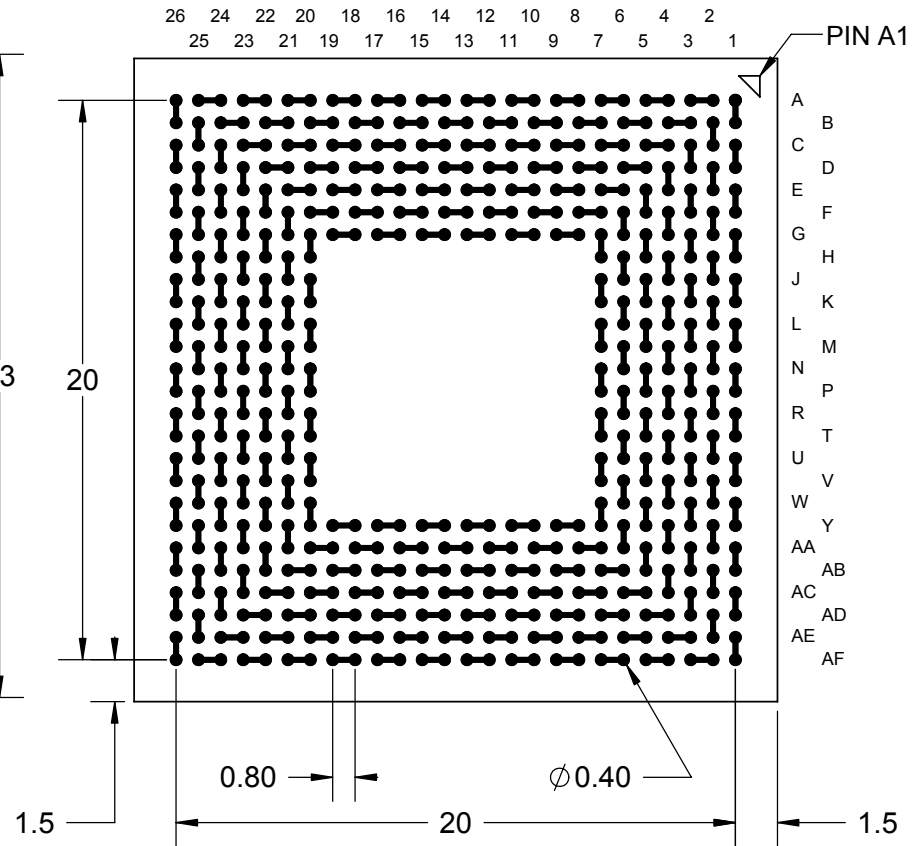


### TOP VIEW



### BALL VIEW



SECTION A-A


Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.40mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.33mm (13 MIL).
- 5) PAD Cu DIAMETER: 0.508mm (20 MIL).
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

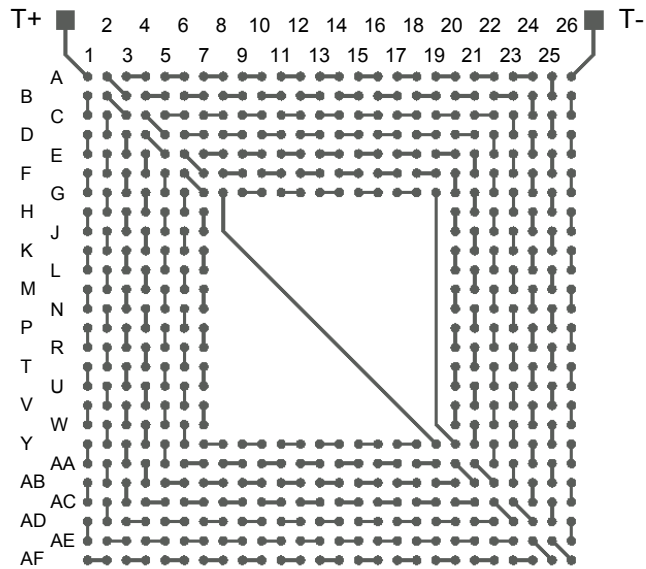
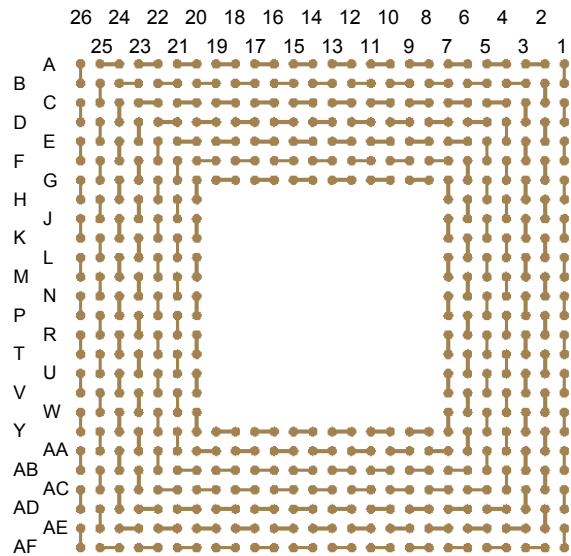
General Table

PART NUMBER TABLE

PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
LBGA532T.8C-DC266D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
LBGA532T.8C-DC266	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	NO
LBGA532T.8-DC266D	Sn63/Pb37	Sn63	NO	YES
LBGA532T.8-DC266	Sn63/Pb37	Sn63	NO	NO

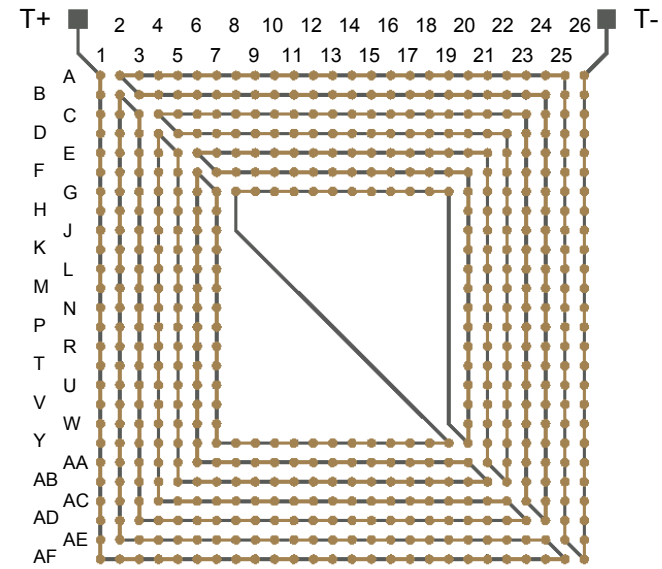
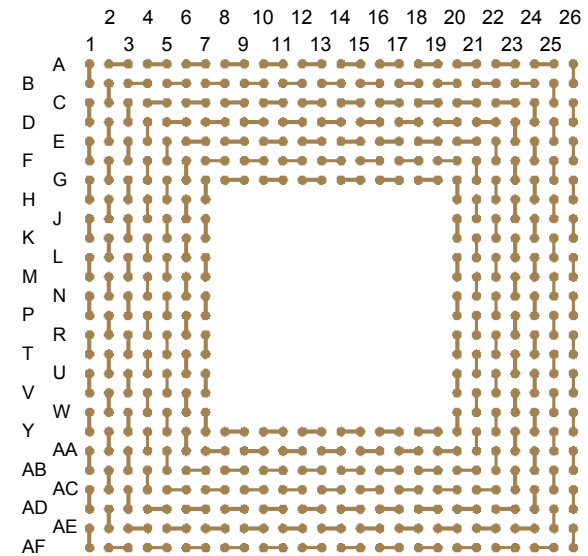
APPROVALS	DATE				
DRAWN T. Au	7/15/2015				
ENG M. Hart	7/15/2015	TITLE BGA532T.8C-DC266 DAISY CHAIN DUMMY			
MFG					
QA		SCALE 3.7:1	SIZE A	DRAWING NO. 582661	REV A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 3
REVISED					

### BALL VIEW



**TEST VEHICLE BOARD**

### BOTTOM SIDE (TOP X-RAY VIEW)



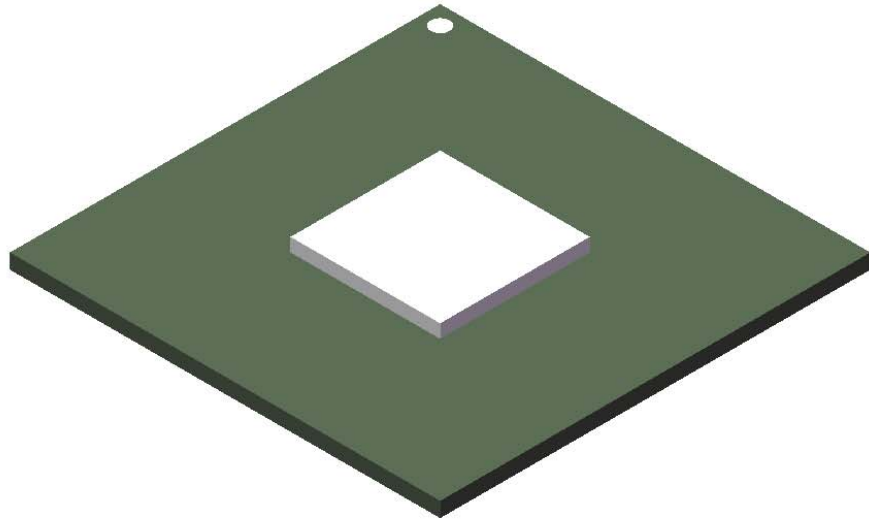
**AFTER MOUNTING**

**Notes:**

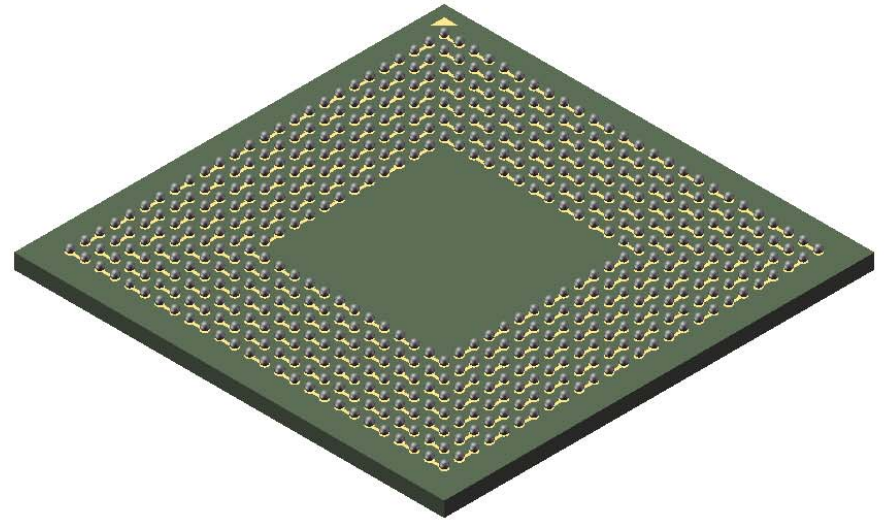
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.508mm (20 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.33mm (13 MIL).



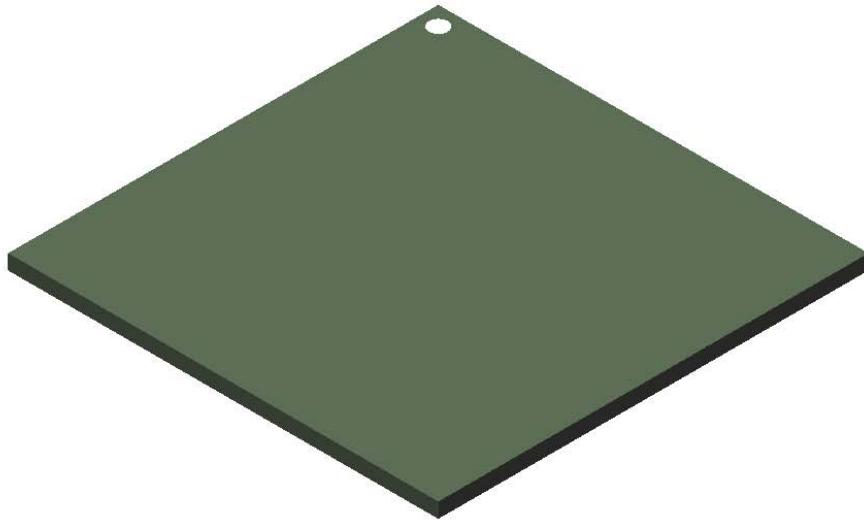
TITLE			
BGA532T.8-DC266 DAISY CHAIN DUMMY			
SCALE	SIZE	DRAWING NO.	REV
3:1	A	582661	A
DO NOT SCALE DRAWING			SHEET 2 OF 3



**TOP  
WITH DIE OPTION  
Suffix "D"**



**BALL VIEW**



**TOP  
WITHOUT DIE OPTION**

**TopLine®**

TITLE BGA532T.8-DC266  
DAISY CHAIN DUMMY

SCALE 3:1	SIZE A	DRAWING NO. 582661	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 3